

HLCC2250G

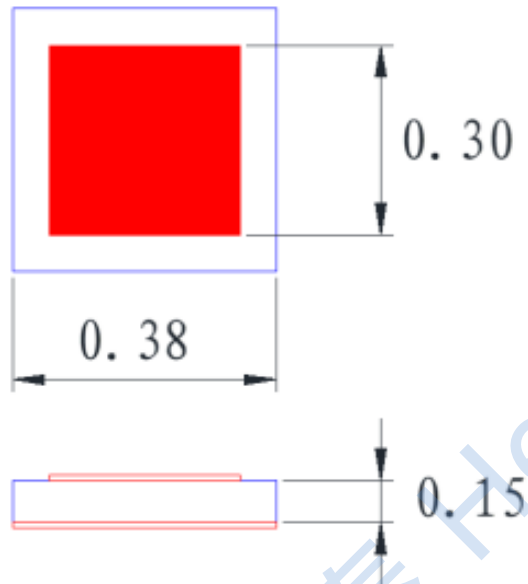
22pF 50V Capacitor

技术参数 (Technical Parameter) :

产品名称 (Product Name)	型号 (Part Number)	电容量 (pF) @1kHz, 1Vrms, 25°C, No DC Bias	最大承受电压 (VDC)	工作温度 (°C)
芯片电容 (Chip Capacitor)	HLCC2250G	22±20%	50	-55~+125

类型 (Type)	镀层：上层 (Upper Layer Coating)	镀层：下层 (Lower Layer Coating)
单面留边型 (Single sided, bottom edge)	TiW-Au 2.5 μm Min	TiW-Pt-Au 2.5 μm Min

外形尺寸 (Dimension) :



备注:

- 1、储存条件(Storage conditions): 温度(Temperature)20-25°C, 湿度(Humidity) 40%-60%;
- 2、适用于粘接工艺, 导电胶H20E, 120°C烘烤30分钟 (Suitable for bonding process, conductive adhesive H20E, baked at 120 °C for 30 minutes) ;
- 3、焊丝的焊接位置应距离电极边缘25 μm或更远, 以避免电极脱落 (The welding position of the welding wire should be 25 μm or further away from the edge of the electrode to avoid electrode detachment) 。

典型测试曲线 (Typical Test Curve) :

